

Product / Process Change Notification



N° 2016-108-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Third source wafer fab for capacity extension in the chip production of 1200V IGBTs 3rd generation of the E3 variant in Hsinchu, Taiwan (additional Products).

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2. January 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: **"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► **Products affected:** Please refer to 1_cip16108_a

► **Detailed Change Information:**

Subject: Implementation of third source wafer fab of IGBT products. (additional Products ref. PCN 2013-183-A).
Individual module material number.

Reason: Capacity extension of 1200V IGBT3-E3

Description:	<u>Old</u>	<u>New</u>
	■ Front End Villach	■ Front End Villach
	■ Front End Kulim	■ Front End Kulim
		■ Front End Hsinchu

► **Product Identification:** Individual module material number.
See attached list 1_cip16108 of affected products.

► **Impact of Change:** Third source IGBT chip fab for 1200V IGBT3-E3. FE plants Villach, Kulim, Hsinchu produce as joint production and may be delivered. Locations of the backend productions of the IGBT modules are unchanged.
The a.m. products / IGBT modules with IGBT chips from Villach, Kulim and Hsinchu have identical specifications according to JEDEC46: fit, form, function and reliability.
Minor Change

► **Attachments:** See PCN 2013-183-A

► **Time Schedule:**

■ Intended start of delivery: 2017-05-01 or direct after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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Third source wafer fab for capacity extension in the chip production of 1200V IGBTs 3rd generation of the E3 variant in Hsinchu, Taiwan (additional Products).



Sales Name	SP number	OPN	Package	Mat. No. 1	Mat. No. 2
FF450R12ME3	SP000317626	FF450R12ME3BOSA1	AG-ECONOD-3-1	30011	43180
FP10R12YT3	SP000100303	FP10R12YT3BOMA1	AG-EASY2-1-1	41393	43161
FP10R12YT3_B4	SP000100350	FP10R12YT3B4BOMA1	AG-EASY2-1-1	41394	43162
FP15R12KE3	SP000100275	FP15R12KE3BOMA1	AG-EASY2-1-1	41395	43163
FP15R12YT3	SP000100304	FP15R12YT3BOMA1	AG-EASY2-1-1	41396	43164
FP25R12KE3	SP000100411	FP25R12KE3BOSA1	AG-ECONO2-5-1	20219	43165
FP25R12KT3	SP000100446	FP25R12KT3BOSA1	AG-ECONO2-5-1	24887	43166
FP40R12KE3	SP000083565	FP40R12KE3BOSA1	AG-ECONO2-5-1	20589	43167
FP40R12KE3G	SP000100420	FP40R12KE3GBOSA1	AG-ECONO3-3-1	21335	43174
FP40R12KT3	SP000100447	FP40R12KT3BOSA1	AG-ECONO2-5-1	24888	43168
FP40R12KT3G	SP000100442	FP40R12KT3GBOSA1	AG-ECONO3-3-1	24564	43175
FP50R12KE3	SP000101740	FP50R12KE3BOSA1	AG-ECONO3-3-1	20594	43176
FP75R12KE3	SP000100415	FP75R12KE3BOSA1	AG-ECONO3-3-1	20599	43177
FS50R12KE3	SP000100413	FS50R12KE3BOSA1	AG-ECONO2-6-1	20384	43169
FS75R12KE3	SP000100414	FS75R12KE3BOSA1	AG-ECONO2-6-1	20385	43170
FS75R12KE3_B9	SP000396438	FS75R12KE3B9BDLA1	AG-ECONO2-6-1	29509	43172
FS75R12KE3_B9	SP000721046	FS75R12KE3B9BOSA1	AG-ECONO2-6-1	33596	43171
FT150R12KE3_B5	SP000551174	FT150R12KE3B5BDLA1	AG-ECONO2-6-1	33097	43173

